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AMENDMENTS TO THE SPECIFICATION

At page 2, kindly amend the paragraph comprising lines 5-10 as indicated:

-- In many prior art techniques, copper is electrodeposited on a copper seed layer which in turn is deposited onto a diffusion barrier layer. Both diffusion barrier and Cu seed layer are typically deposited using physical vapor deposition (PVD), ionized physical vapor deposition (IPVD), or chemical vapor deposition (CVD) techniques (Hu et al., Mat.Chem. Phys., 52 1998)5). All of these methods, PVD, IPVD, and CVD require special tooling along with a vacuum. --

At page 3, following the description of Figure 2, kindly insert the following material:

B2 -- Figure 3 is a cross-sectional view of a line or via opening with a blanket deposit of a barrier material. --

At page 4, kindly amend the paragraph comprising lines 14-17 as follows:

B3 -- A copper or copper alloy layer 5 (not shown) can be deposited directly onto the diffusion barrier layer 4. The copper can be deposited directly on the barrier layer 4 without any additional seed layer by electrodeposition from a plating bath having a pH of about 12.89 or more. The copper plating is employed to fill the lines and/or vias openings 3. --

At page 5, kindly amend the paragraph comprising lines 1-5 as follows:

B4 -- The electroplating is carried out employing a current density of about 5 to about 25  $\mu\text{A}/\text{cm}^2$  and preferably about 10 to about 20  $\mu\text{A}/\text{cm}^2$  20  $\mu\text{A}/\text{cm}^2$ . The electroplating composition typically contains about 0.02M to about 0.211M (molar) of a copper salt such as  $\text{CuSO}_4$  and about

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0.02M to about 0.51M of a complexing agent such as Na<sub>2</sub>EDTA (sodium salt of ethylene diamine tetraacetic acid, Na<sub>2</sub>EDTA (sodium salt of ethylene diamine tetraacetic acid). --

At page 6, kindly amend line 7 as follows:

B5  
- Na<sub>2</sub>EDTA Na<sub>2</sub>EDTA ..... 37.2 g/L